## Microelectronics & MEMS Laboratory, IIT Madras

## **EQUIPMENT USAGE CHARGES**

SI. No	Process/Test	Equipment	Industrial User
INO	L10/G22\ 1G2{	Equipment	(INR/hr)*
1	Wire bonding	Wire bonding system	4,000
2	Wafer dicing	Wafer dicing system	4,000
3	Electrical characterization (DC-30 MHz) at different temperatures (-60 to +200C)	DC probe station (w/ thermal chuck), Parametric Analyzer, Impedance analyzer	4,000
4	Electrical characterization (DC-30MHZ) at room temperature	DC probe station (w/o thermal chuck), Parametric Analyzer, Impedance analyzer	2,000
5	Electrical characterization (RF) at different temperatures (-60 to +200C)	RF probe station (w/ thermal chuck), Vector Network Analyzer	4,000
6	Electrical characterization (RF) at room temperature	RF probe station (w/o thermal chuck), Vector Network Analyzer	4,000
7	Electrical characterization in vacuum at different temperatures (-60 to +200C)	Vacuum probe station (w/ thermal chuck), Parametric Analyzer, Impedance analyzer, Vector Network Analyzer	4,000
8	Surface Profile Measurements	Non-contact surface profiler	2,000
9	In-plane / out of plane vibration and surface topography	Micro System Analyzer including Laser Doppler Vibrometer	2,000
10	Thickness/Refractive Index measurements	Spectroscopic Ellipsometer	2,000
11	Surface imaging	Mini SEM	2,000
12	Surface imaging	Confocal Microscope	2,000

<sup>\*</sup>External Academics/Startups/IITM Research Park Firms – 50% discount

<sup>\*</sup>IITM Users - 75% discount